

Title (en)

ELECTRIC COMPONENT, METHOD FOR THE PRODUCTION THEREOF, AND ITS USE

Title (de)

ELEKTRISCHES BAUELEMENT, VERFAHREN ZU DESSEN HERSTELLUNG UND DESSEN VERWENDUNG

Title (fr)

COMPOSANT ELECTRIQUE, SON PROCEDE DE FABRICATION ET SON UTILISATION

Publication

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Application

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Abstract (en)

[origin: WO0219467A1] The invention relates to an electric component comprising a base body (1), which has a top side and a bottom side and which is at least partially comprised of a dielectric. On said top side, a raised or recessed delimiting structure (2) delimits a top contact surface (3) that is covered by a top contact layer (4). Said bottom side comprises two bottom contact surfaces (5, 6), which are insulated from one another and which are each covered by a bottom contact layer (7, 8). One of the bottom contact layers (5, 6) is connected in an electrically conductive manner to the top contact layer (4) via a connecting element (9) extending inside the base body (1). The invention also relates to a method for producing said component and to the use thereof. The inventive component is advantageous in that the top contact surface (3) can be easily applied with a defined size by using screen printing or vapor deposition. This enables the easy production of antennas with defined characteristics such as frequency position and input impedance.

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